
Toplotno načrtovanje elektronskih sklopov z miniaturiziranimi napravami za površinsko montažo in s tem povezane meritve

Thermal design of electronics assemblies with miniaturised surface mounting devices and related measurements

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ICS:

31.180	Tiskana vezja (TIV) in tiskane plošče	Printed circuits and boards
31.190	Sestavljeni elektronski elementi	Electronic component assemblies

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91/2127/CDV

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TITLE:

Thermal design of electronics assemblies with miniaturised surface mounting devices and related measurements - Part 2: Method for evaluating thermal conductivity of circuit boards with polymer composites by using finite element analysis and measurements

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**THERMAL DESIGN OF ELECTRONICS ASSEMBLIES WITH MINIATURISED
SURFACE MOUNTING DEVICES AND RELATED MEASUREMENTS****Part 2: Method for evaluating thermal conductivity of circuit boards with
polymer composites by using finite element analysis and measurements**

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Draft	Report on voting
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131
132 Full information on the voting for its approval can be found in the report on voting indicated in
133 the above table.

134 The language used for the development of this International Standard is English.

135 This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in
136 accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, and the
137 ISO/IEC Directives available at www.iec.ch/members_experts/refdocs. The main document
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139 A list of all parts in the IEC 63609 series, published under the general title *Thermal design of*
140 *electronics assemblies with miniaturised surface mounting devices and related measurements*,
141 can be found on the IEC website.

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